

5555 NE Moore Ct. Hillsboro OR 97124 custreq@latticesemi.com April , 2025	Package: 410 FOWLP Total Device Weight 183.723 milligram				Package Code: ASGA410 Products: LAV-AT-E30		Assembly: ASEKH Size (mm): 9.0x11.0x0.84 Lead pitch (mm): 0.5 MSL: 3 Reflow max (°C): 260°C	
	% of Total Pkg. Wt.	Weight (g)	% of Total Pkg. Wt.	Weight (mg)	Substance	CAS #	% of Subst.	Notes / Assumptions:
	Die	47.998%	88.183	47.998%	88.183	Silicon chip	7440-21-3	100.000%
Molding Compound	20.634%	37.910	15.546% 3.109% 0.114% 0.622% 0.622% 0.622%	28.561 5.712 0.209 1.142 1.142 1.142	Silica(Amorphous) A Silica(Amorphous) B Carbon Black Proprietary Epoxy Resin A Proprietary Epoxy Resin B Proprietary Phenol Resin	60676-86-0 7631-86-9 1333-86-4 Proprietary Proprietary Proprietary	75.339% 15.068% 0.552% 3.014% 3.014% 3.014%	Sumitomo EME-QXG01
Repassivation Polyimide (LTC9320-E07)	0.446%	0.820	0.204% 0.057% 0.023% 0.005% 0.158%	0.374 0.104 0.042 0.010 0.291	Gamma-butyrolactone Dimethyl sulfoxide Tetraethylene Glycol Dimethacrylate 1- [4- (Phenylthio)phenyl]-1,2-octanedione 2- (O-benzoyloxime) Poly(aromatic ether amide) acid ester	96-48-0 67-68-5 109-17-1 253585-83-0 Proprietary	45.616% 12.671% 5.068% 1.166% 35.479%	Polyamic Ester. LTC9320-E07
RDL1	0.015%	0.027	0.015%	0.027	Titanium (Ti)	7440-32-6	100.000%	Titanium (Ti)
	1.241%	2.280	1.241%	2.280	Copper (Cu)	7440-50-8	100.000%	Copper (Cu)
Repassivation Polyimide (LTC9320-E07)	0.762%	1.400	0.348% 0.097% 0.039% 0.009% 0.270%	0.639 0.177 0.071 0.016 0.497	Gamma-butyrolactone Dimethyl sulfoxide Tetraethylene Glycol Dimethacrylate 1- [4- (Phenylthio)phenyl]-1,2-octanedione 2- (O-benzoyloxime) Poly(aromatic ether amide) acid ester	96-48-0 67-68-5 109-17-1 253585-83-0 Proprietary	45.62% 12.67% 5.07% 1.17% 35.48%	Polyamic Ester. LTC9320-E07
RDL2	0.017%	0.031	0.017%	0.031	Titanium (Ti)	7440-32-6	100.000%	Titanium (Ti)
	3.132%	5.754	3.132%	5.754	Copper (Cu)	7440-50-8	100.000%	Copper (Cu)
Repassivation Polyimide (LTC9320-E07)	0.885%	1.627	0.404% 0.112% 0.045% 0.010% 0.314%	0.742 0.206 0.082 0.019 0.577	Gamma-butyrolactone Dimethyl sulfoxide Tetraethylene Glycol Dimethacrylate 1- [4- (Phenylthio)phenyl]-1,2-octanedione 2- (O-benzoyloxime) Poly(aromatic ether amide) acid ester	96-48-0 67-68-5 109-17-1 253585-83-0 Proprietary	45.616% 12.671% 5.068% 1.166% 35.479%	Polyamic Ester. LTC9320-E07
UBM	0.006%	0.012	0.006%	0.012	Titanium (Ti)	7440-32-6	100.000%	Titanium (Ti)
	1.126%	2.069	1.126%	2.069	Copper (Cu)	7440-50-8	100.000%	Copper (Cu)
Bump	23.737%	43.611	22.174% 0.708% 0.130% 0.012% 0.708% 0.006%	40.739 1.300 0.238 0.022 1.300 0.011	Tin Silver Copper Nickel Bismuth Germanium	7440-31-5 7440-22-4 7440-50-8 7440-02-0 7440-69-9 7440-56-4	93.416% 2.981% 0.547% 0.050% 2.981% 0.025%	

Notes:

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